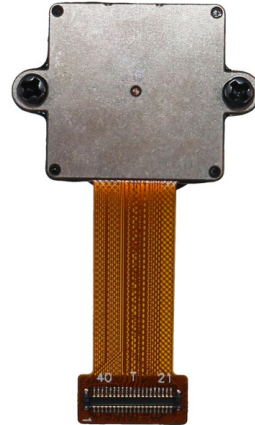


## YDS-B9MF-IMX577 V1.0

### 12.3MP Sony IMX577 MIPI Interface M12 Fixed Focus Camera Module



Front View



Back View

#### Specifications

<b>Camera Module No.</b>	<b>YDS-B9MF-IMX577 V1.0</b>
<b>Resolution</b>	12.3MP
<b>Image Sensor</b>	IMX577
<b>Sensor Type</b>	1/2.3"
<b>Pixel Size</b>	1.55 um x 1.55 um
<b>EFL</b>	3.00 mm
<b>F.NO</b>	2.80
<b>Pixel</b>	4056 x 3040
<b>View Angle</b>	166.0°(DFOV) 120.0°(HFOV) 89.0°(VFOV)
<b>Lens Dimensions</b>	17.20 x 17.20 x 22.40 mm
<b>Module Size</b>	42.09 x 24.20 mm
<b>Module Type</b>	Fixed Focus
<b>Interface</b>	MIPI
<b>Auto Focus VCM Driver IC</b>	None
<b>Lens Model</b>	YDS-LENS-MJ7016B
<b>Lens Type</b>	650nm IR Cut
<b>Operating Temperature</b>	-10°C to +70°C
<b>Mating Connector</b>	AXE540124



## YDS-B9MF-IMX577 V1.0

### 12.3MP Sony IMX577 MIPI Interface M12 Fixed Focus Camera Module



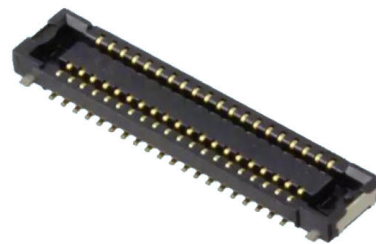
Top View



Side View

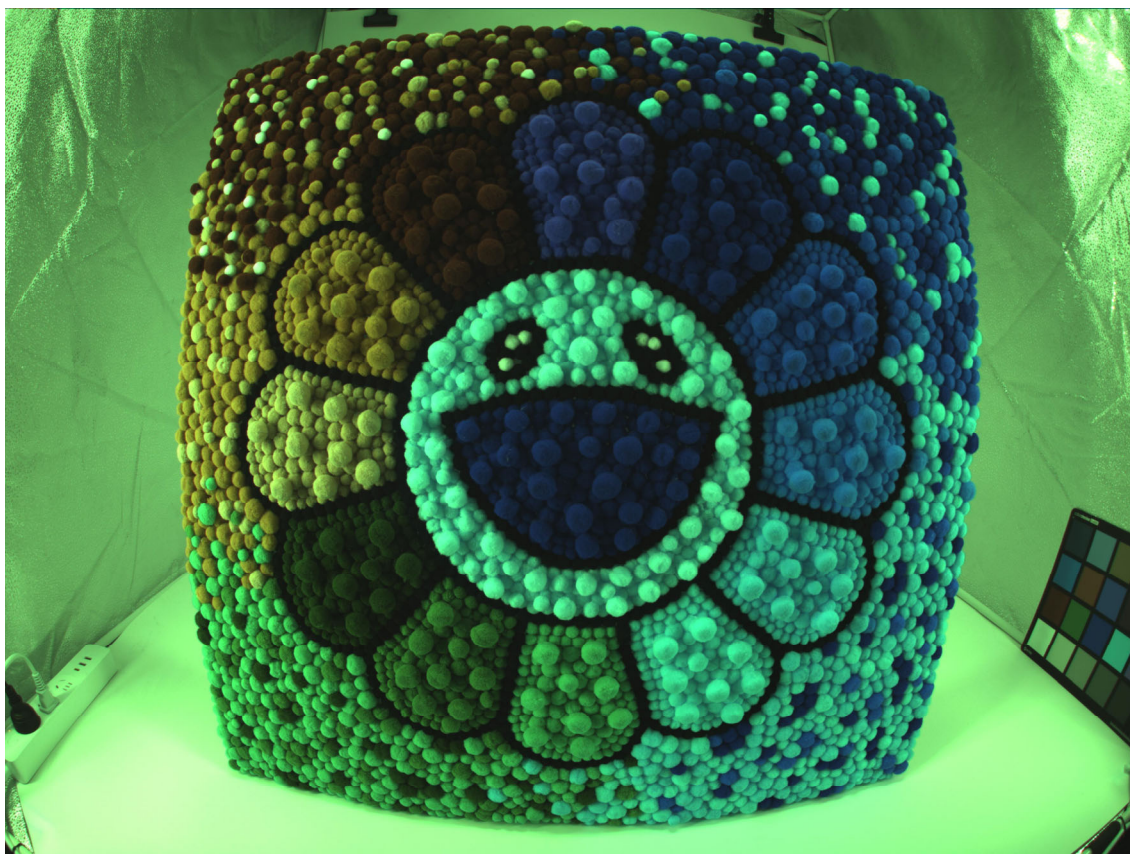
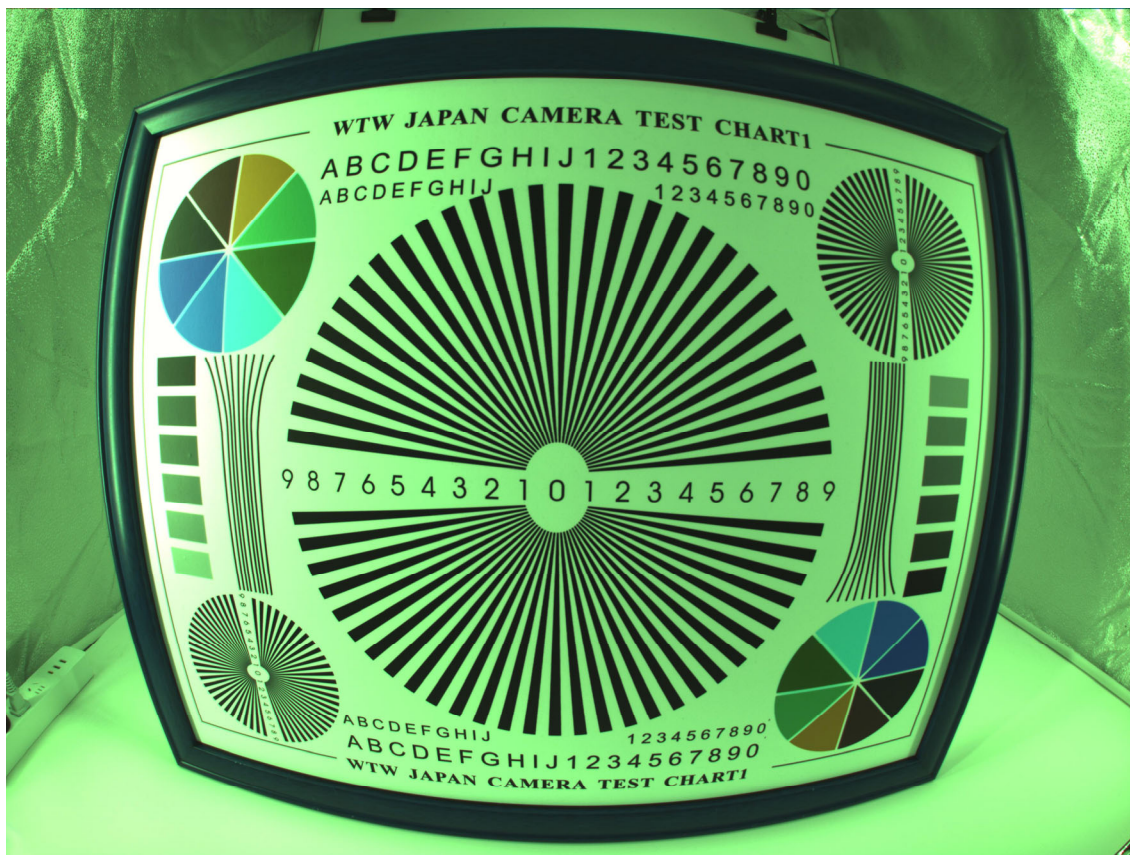


Bottom View

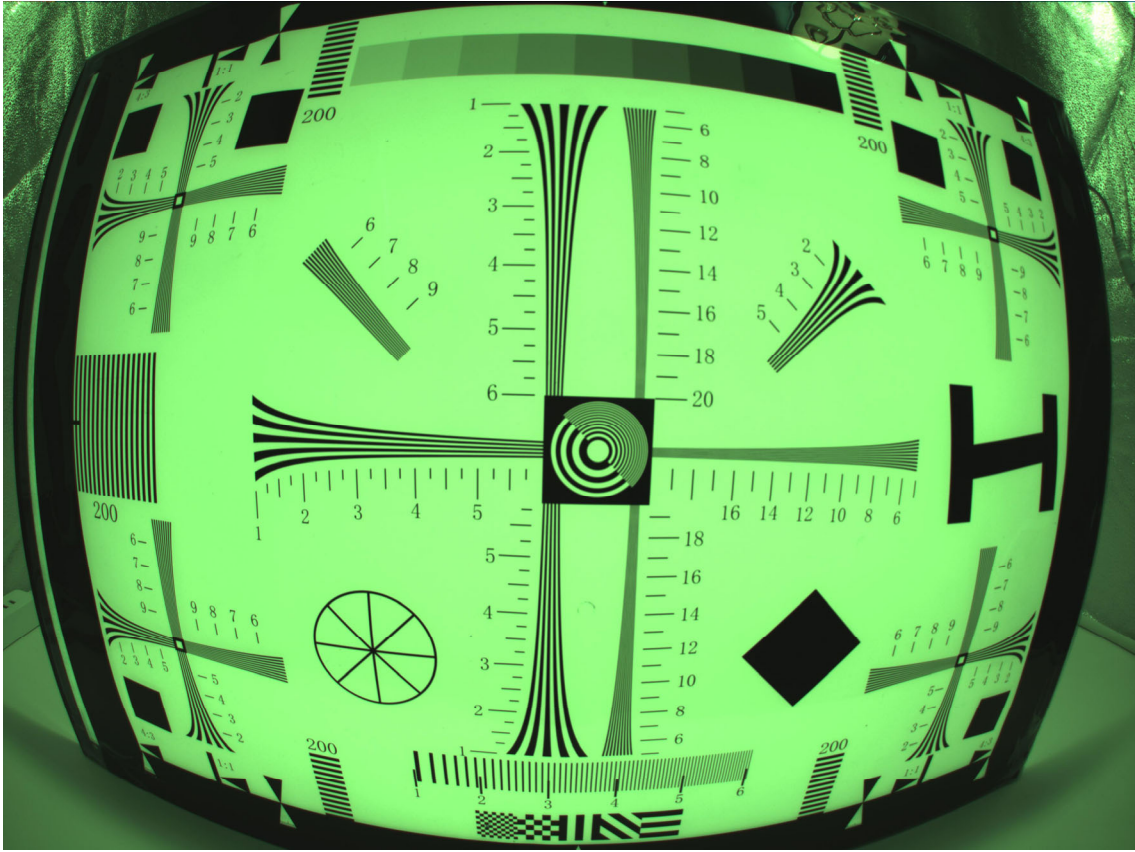


Mating Connector

**Real Test Images**  
**B9MF-IMX577 V1.0**



**Real Test Images  
B9MF-IMX577 V1.0**



**Real Test Images**  
**B9MF-IMX577 V1.0**



# ROHS

## PIN SIGNAL

1	SLASEL
2	PWMDN
3	DGND
4	DMO1P
5	DMO1N
6	DGND
7	DMO2P
8	DMO2N
9	DGND
10	DMO3P
11	DMO3N
12	DGND
13	DMO4P
14	DMO4N
15	DGND
16	DCKP
17	DCKN
18	NC
19	NC
20	NC
21	NC
22	NC
23	NC
24	NC
25	SCL
26	SDA
27	DGND
28	INCK
29	DVDD 1.05V
30	DOVDD 1.8V
31	DGND
32	AVDD 2.8V
33	AGND
34	DGND
35	NC
36	NC
37	NC
38	NC
39	DGND
40	DGND

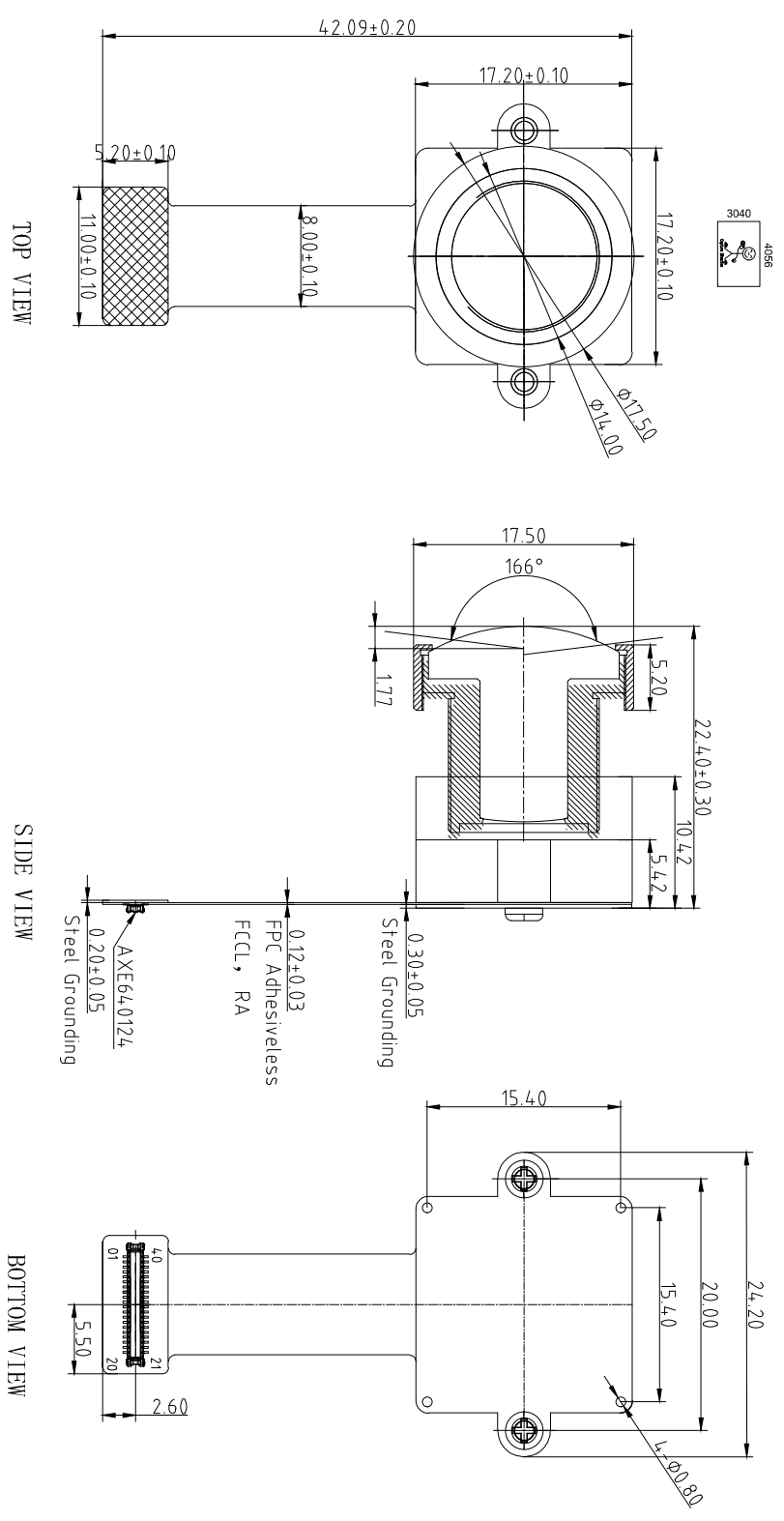
### Parameters:

#### 1、Sensor specification:

Image Sensor: IMX577-AAACK-C  
 Pixel: 155um×155um  
 Lens Type: 1/2.3  
 Important Voltage Description: DVDD1.05V  
 (External power supply);

#### 2、Lens specification:

FOV: 166° (D); 120° (H); 89° (V)  
 F/NO.: 2.8  
 TV distortion: <35%  
 Focal length: 3mm  
 Composition: 7G+IR FILTER  
 IR Cut Coating: 650nm±10nm@50%



Version	Information	Date
V1.0	First Version	5-8-2020

Designed By	Kevin	Model Name:	B9MF-IMX577 V1.0		
Checked By	Aouly Yan	Projection Type:	Unit:	Material:	-----
		Third Angle	mm	Sheet:	1 of 1
			Scale:	Version:	1/0
			1:1		

## [Product Information]

Ver.1.0

# IMX577-AACK

Diagonal 7.857 mm (Type 1/2.3) 12.3 Mega-Pixel CMOS Image Sensor with Square Pixel for Color Cameras

---

### Description

The IMX577-AACK is a diagonal 7.857 mm (Type 1/2.3) 12.3 Mega-pixel CMOS active pixel type stacked image sensor with a square pixel array. It adopts Sony's Stacked CMOS Image Sensor technology to achieve high speed image capturing by column parallel A/D converter circuits and high sensitivity and low noise image (comparing with conventional CMOS image sensor) through the backside illuminated imaging pixel structure. R, G, and B pigment primary color mosaic filter is employed. It equips an electronic shutter with variable integration time. It operates with three power supply voltages: analog 2.8 V, digital 1.05 V and 1.8 V for input/output interface and achieves low power consumption.

In addition, this product is designed for use in consumer use camcorder. When using this for another application, Sony Semiconductor Solutions Corporation does not guarantee the quality and reliability of product. Therefore, don't use this for applications other than consumer use camcorder.

In addition, individual specification change cannot be supported because this is a standard product.

Consult your Sony Semiconductor Solutions Corporation sales representative if you have any questions.

---

### Features

- ◆ Back-illuminated and stacked CMOS image sensor
- ◆ Digital Overlap High Dynamic Range (DOL-HDR) mode with raw data output.
- ◆ High signal to noise ratio (SNR).
- ◆ Full resolution @60 frame/s (Normal), 4K2K @60 frame/s (Normal), 1080p @240 frame/s  
Full resolution @40 frame/s (12 bit Normal), Full resolution @30 frame/s (DOL-HDR, 2 frame)
- ◆ Output video format of RAW12/10/8, COMP8.
- ◆ Power Save Mode with MIPI ULPS operation
- ◆ Pixel binning readout and V sub-sampling function.
- ◆ Independent flipping and mirroring.
- ◆ Input clock frequency 6 to 27 MHz
- ◆ CSI-2 serial data output (MIPI 2lane/4lane, Max. 2.1 Gbps/lane, D-PHY spec. ver. 1.2 compliant)
- ◆ 2-wire serial communication.
- ◆ Two PLLs for independent clock generation for pixel control and data output interface.
- ◆ Defect Pixel Correction (DPC)
- ◆ Ambient Light Sensor (ALS)
- ◆ Fast mode transition. (on the fly)
- ◆ Dual sensor synchronization operation (Multi camera compatible)
- ◆ 7 k bit of OTP ROM for users.
- ◆ Built-in temperature sensor
- ◆ 10-bit/12-bit A/D conversion on chip
- ◆ Horizontal Low Power Analog Cropping
- ◆ Window Scanning mode
- ◆ 92-pin high-precision ceramic package

Sony reserves the right to change products and specifications without prior notice.

Sony logo is a registered trademark of Sony Corporation.

## Device Structure

◆ CMOS image sensor	
◆ Image size	Diagonal 7.857 mm (Type 1/2.3)
◆ Total number of pixels	4072 (H) × 3176 (V) approx. 12.93 M pixels
◆ Number of effective pixels	4072 (H) × 3064 (V) approx. 12.47 M pixels
◆ Number of active pixels	4056 (H) × 3040 (V) approx. 12.33 M pixels
◆ Chip size	7.564 mm (H) × 5.476 mm (V)
◆ Unit cell size	1.55 μm (H) × 1.55 μm (V)
◆ Package	92 pin LGA

## Image Sensor Characteristics

(T<sub>j</sub> = 60 °C)

Item		Value	Remarks
Sensitivity (F2.8)	Min.	250 LSB	1/120 s integration
Saturation signal	Min.	1023 LSB	

## Basic Drive Mode

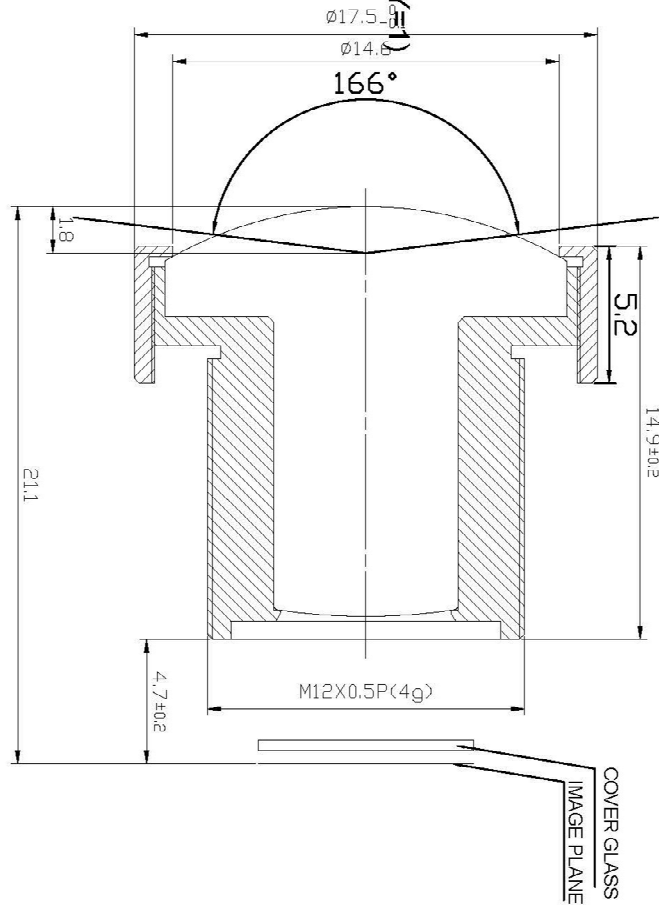
Drive mode	Number of active pixels	Maximum frame rate [frame/s]	Output interface	ADC [bit]
Full (4:3) (Normal)	4056 (H) × 3040 (V) approx. 12.33 M pixels	60	CSI-2	10
		43	CSI-2	12
Full (4:3) (DOL-HDR)	4056 (H) × 3040 (V) approx. 12.33 M pixels	DOL 2 frame : 30 DOL 3 frame : 15	CSI-2	10
Full (16:9) 4K2K (Normal)	4056 (H) × 2288 (V) approx. 9.28 M pixels	79	CSI-2	10
Full (16:9) 4K2K (DOL-HDR)	4056 (H) × 2288 (V) approx. 9.28 M pixels	DOL 2 frame : 39 DOL 3 frame : 19	CSI-2	10
Full (4:3) Binning (Normal)	2028 (H) × 1520 (V) approx. 3.08 M pixels	178	CSI-2	10
Full (16:9) Binning 1080P (Normal)	2028 (H) × 1112 (V) approx. 2.26 M pixels	241	CSI-2	10
Full (16:9) Binning 720P (Normal)	1352 (H) × 740 (V) approx. 1.00 M pixels	241	CSI-2	10
Full (16:9) Scaling 1080P (Normal)	2028 (H) × 1144 (V) approx. 2.32 M pixels	79	CSI-2	10
Full (16:9) Scaling 720P (Normal)	1352 (H) × 762 (V) approx. 1.03 M pixels	79	CSI-2	10



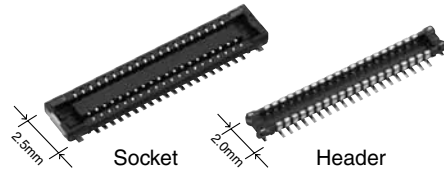
## YDS-LENS-MJ7016B

### SPECIFICATION

1. FOR 1/2.3" 16M SENSOR
2. IMAGE HEIGHT  $\varnothing 8$
3. EFL = 3mm
4. WORKING F/NO. = 2.8
5. BFL = 5.03mm
6. FOV = 166°  
H = 120°  
V = 89°
7. DISTORTION = 35%
8. RELATIVE ILLUMINATION = 72% (Y=1)
9. CONSTRUCTION: 7G
10. THREAD : M12X0.5P
11. IR FILTER 650± 10nm



①	修改记录 RECORD	姓名 NAME	日期 DATE	单位 UNIT	比例 SCALE	图形符号 DRAWING NO.	图次 REV.	审核 CHECKED	日期 DATE
②									
③									
④									
⑤									



RoHS compliant

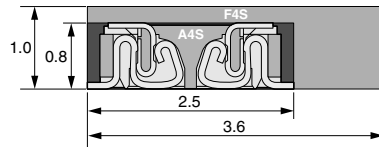
For board-to-FPC

## Narrow pitch connectors (0.4mm pitch)

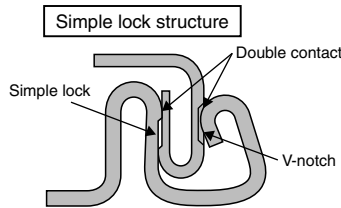
# A4S Series

### FEATURES

- 2.5 mm wide slim two-piece style connectors**  
Compact and slim structure contributes overall miniaturization of product design.  
<Compared to F4S series (40 pin contacts, when mated)>
  - Width: 30% down
  - Footprint: 30% down



- "TOUGH CONTACT ADVANCED" ensures high resistance to various environments in lieu of slim and low profile body**
- Simple lock structure provides tactile feedback to ensure excellent mating/unmating operation feel.**



The connector gives the tactile feedback when inserted, allowing reliable mating.

- Mated heights of 0.8 and 1.0 mm are available for the same foot pattern.**
- Connectors for inspection available**

### APPLICATIONS

Recommended for board-to-FPC connections of mobile equipment, such as cellular phones, smart phones, laptops, and portable music players

## ORDERING INFORMATION

	AXE				2	4
5: Narrow Pitch Connector A4S (0.4 mm pitch) Socket						
6: Narrow Pitch Connector A4S (0.4 mm pitch) Header						
Number of pins (2 digits)						
Mated height <Socket> 1: For mated height 0.8/1.0 mm <Header> 1: For mated height 0.8 mm 2: For mated height 1.0 mm						
Functions 2: Without positioning bosses						
Surface treatment (Contact portion / Terminal portion) <Socket> 4: Ni plating on base, Au plating on surface (for Ni barrier available) <Header> 4: Ni plating on base, Au plating on surface						

**PRODUCT TYPES**

Mated height	Number of pins	Part number		Packing	
		Socket	Header	Inner carton (1-reel)	Outer carton
0.8mm	10	AXE510124	AXE610124	5,000 pieces	10,000 pieces
	12	AXE512124	AXE612124		
	14	AXE514124	AXE614124		
	16	AXE516124	AXE616124		
	18	AXE518124	AXE618124		
	20	AXE520124	AXE620124		
	22	AXE522124	AXE622124		
	24	AXE524124	AXE624124		
	26	AXE526124	AXE626124		
	28	AXE528124	AXE628124		
	30	AXE530124	AXE630124		
	32	AXE532124	AXE632124		
	34	AXE534124	AXE634124		
	36	AXE536124	AXE636124		
	38	AXE538124	AXE638124		
	40	AXE540124	AXE640124		
	44	AXE544124	AXE644124		
	50	AXE550124	AXE650124		
	54	AXE554124	AXE654124		
	1.0mm	56	AXE556124		
60		AXE560124	AXE660124		
64		AXE564124	AXE664124		
70		AXE570124	AXE670124		
80		AXE580124	AXE680124		
10		AXE510124	AXE610224		
12		AXE512124	AXE612224		
14		AXE514124	AXE614224		
20		AXE520124	AXE620224		
24		AXE524124	AXE624224		
26		AXE526124	AXE626224		
30		AXE530124	AXE630224		
32		AXE532124	AXE632224		
40		AXE540124	AXE640224		
44		AXE544124	AXE644224		
50		AXE550124	AXE650224		
54	AXE554124	AXE654224			
60	AXE560124	AXE660224			
70	AXE570124	AXE670224			
80	AXE580124	AXE680224			

Notes: 1. Order unit:

For volume production: 1-inner carton (1-reel) units

Samples for mounting check: 50-connector units. Please contact our sales office.

Samples: Small lot orders are possible. Please contact our sales office.

- The above part numbers are for connectors without positioning bosses, which are standard. When ordering connectors with positioning bosses, please contact our sales office.
- Please contact us for connectors having a number of pins other than those listed above.

# AXE5, 6

## SPECIFICATIONS

### ■ Characteristics

	Item	Specifications	Conditions
Electrical characteristics	Rated current	0.3A/pin contact (Max. 5 A at total pin contacts)	
	Rated voltage	60V AC/DC	
	Breakdown voltage	150V AC for 1 min.	No short-circuiting or damage at a detection current of 1 mA when the specified voltage is applied for one minute.
	Insulation resistance	Min. 1,000MΩ (initial)	Using 250V DC megger (applied for 1 min.)
	Contact resistance	Max. 90mΩ	Based on the contact resistance measurement method specified by JIS C 5402.
Mechanical characteristics	Composite insertion force	Max. 1.200N/pin contacts × pin contacts (initial)	
	Composite removal force	Min. 0.165N/pin contacts × pin contacts	
	Contact holding force (Socket contact)	Min. 0.20N/pin contacts	Measuring the maximum force. As the contact is axially pull out.
Environmental characteristics	Ambient temperature	-55°C to +85°C	No freezing at low temperatures. No dew condensation.
	Soldering heat resistance	Peak temperature: 260°C or less (on the surface of the PC board around the connector terminals)	Infrared reflow soldering
		300°C within 5 sec. 350°C within 3 sec.	Soldering iron
	Storage temperature	-55°C to +85°C (product only) -40°C to +50°C (emboss packing)	No freezing at low temperatures. No dew condensation.
	Thermal shock resistance (header and socket mated)	5 cycles, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Sequence 1. -55 <sup>±3</sup> °C, 30 minutes 2. ~, Max. 5 minutes 3. 85 <sup>±3</sup> °C, 30 minutes 4. ~, Max. 5 minutes
	Humidity resistance (header and socket mated)	120 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Bath temperature 40±2°C, humidity 90 to 95% R.H.
	Saltwater spray resistance (header and socket mated)	24 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩ	Bath temperature 35±2°C, saltwater concentration 5±1%
H <sub>2</sub> S resistance (header and socket mated)	48 hours, contact resistance max. 90mΩ	Bath temperature 40±2°C, gas concentration 3±1 ppm, humidity 75 to 80% R.H.	
Lifetime characteristics	Insertion and removal life	30 times	Repeated insertion and removal speed of max. 200 times/hours
Unit weight		20 pin contact type: Socket: 0.02 g Header: 0.01 g	

### ■ Material and surface treatment

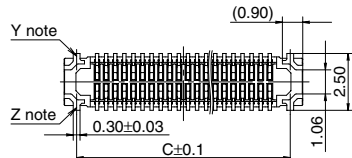
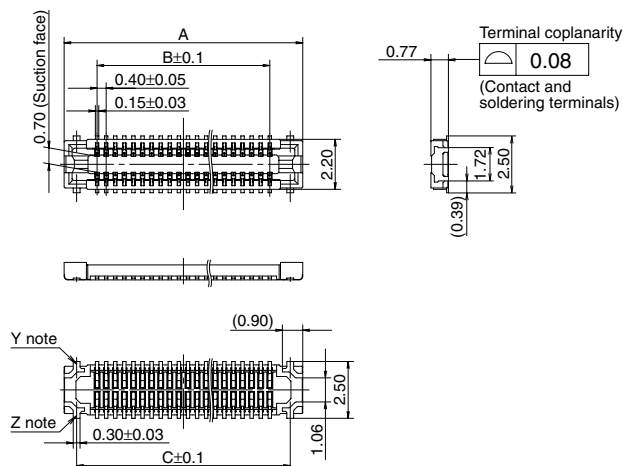
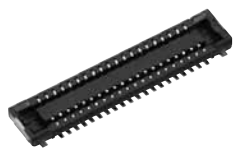
Part name	Material	Surface treatment
Molded portion	LCP resin (UL94V-0)	—
Contact and Post	Copper alloy	Contact portion: Base: Ni plating Surface: Au plating Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) The socket terminals close to the portion to be soldered have nickel barriers (exposed nickel portions). Soldering terminals: Sockets: Base: Ni plating Surface: Pd+Au flash plating (except the terminal tips) Headers: Base: Ni plating Surface: Au plating (except the terminal tips)

**DIMENSIONS** (Unit: mm)

The CAD data of the products with a **CAD Data** mark can be downloaded from: <http://industrial.panasonic.com/ac/e>

**Socket (Mated height: 0.8 mm/1.0 mm)**

**CAD Data**



General tolerance: ±0.2

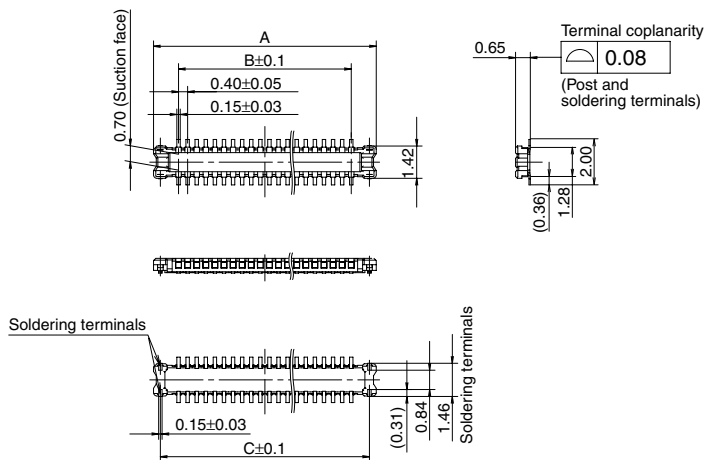
Note: Since the soldering terminals has a single-piece construction, sections Y and Z are electrically connected.

Dimension table (mm)

Number of pins/ dimension	A	B	C
10	4.5	1.6	3.4
12	4.9	2.0	3.8
14	5.3	2.4	4.2
16	5.7	2.8	4.6
18	6.1	3.2	5.0
20	6.5	3.6	5.4
22	6.9	4.0	5.8
24	7.3	4.4	6.2
26	7.7	4.8	6.6
28	8.1	5.2	7.0
30	8.5	5.6	7.4
32	8.9	6.0	7.8
34	9.3	6.4	8.2
36	9.7	6.8	8.6
38	10.1	7.2	9.0
40	10.5	7.6	9.4
44	11.3	8.4	10.2
50	12.5	9.6	11.4
54	13.3	10.4	12.2
56	13.7	10.8	12.6
60	14.5	11.6	13.4
64	15.3	12.4	14.2
70	16.5	13.6	15.4
80	18.5	15.6	17.4

**Header (Mated height: 0.8 mm)**

**CAD Data**



General tolerance: ±0.2

Dimension table (mm)

Number of pins/ dimension	A	B	C
10	3.8	1.6	3.2
12	4.2	2.0	3.6
14	4.6	2.4	4.0
16	5.0	2.8	4.4
18	5.4	3.2	4.8
20	5.8	3.6	5.2
22	6.2	4.0	5.6
24	6.6	4.4	6.0
26	7.0	4.8	6.4
28	7.4	5.2	6.8
30	7.8	5.6	7.2
32	8.2	6.0	7.6
34	8.6	6.4	8.0
36	9.0	6.8	8.4
38	9.4	7.2	8.8
40	9.8	7.6	9.2
44	10.6	8.4	10.0
50	11.8	9.6	11.2
54	12.6	10.4	12.0
56	13.0	10.8	12.4
60	13.8	11.6	13.2
64	14.6	12.4	14.0
70	15.8	13.6	15.2
80	17.8	15.6	17.2



# YDS CAMERA MODULE

*your best camera partner*

## Camera Module Pinout Definition Reference Chart

OmniVision	Sony	Samsung	On-Semi	Aptina	Himax	GalaxyCore	PixArt	SmartSens	Sensors
Pin Signal		Description							
DGND GND		ground for digital circuit							
AGND		ground for analog circuit							
PCLK DCK		DVP PCLK output							
XCLR PWDN XSHUTDOWN STANDBY		power down active high with internal pull-down resistor							
MCLK XVCLK XCLK INCK		system input clock							
RESET RST		reset active low with internal pull-up resistor							
NC NULL		no connect							
SDA SIO_D SIOD		SCCB data							
SCL SIO_C SIOC		SCCB input clock							
VSYNC XVS FSYNC		DVP VSYNC output							
HREF XHS		DVP HREF output							
DOVDD		power for I/O circuit							
AFVDD		power for VCM circuit							
AVDD		power for analog circuit							
DVDD		power for digital circuit							
STROBE FSTROBE		strobe output							
FSIN		synchronize the VSYNC signal from the other sensor							
SID		SCCB last bit ID input							
ILPWM		mechanical shutter output indicator							
FREQ		frame exposure / mechanical shutter							
GPIO		general purpose inputs							
SLASEL		I2C slave address select							
AFEN		CEN chip enable active high on VCM driver IC							
<b>MIPI Interface</b>									
MDN0 DN0 MD0N DATA_N DMO1N		MIPI 1st data lane negative output							
MDP0 DP0 MD0P DATA_P DMO1P		MIPI 1st data lane positive output							
MDN1 DN1 MD1N DATA2_N DMO2N		MIPI 2nd data lane negative output							
MDP1 DP1 MD1P DATA2_P DMO2P		MIPI 2nd data lane positive output							
MDN2 DN2 MD2N DATA3_N DMO3N		MIPI 3rd data lane negative output							
MDP2 DP2 MD2P DATA3_P DMO3P		MIPI 3rd data lane positive output							
MDN3 DN3 MD3N DATA4_N DMO4N		MIPI 4th data lane negative output							
MDP3 DP3 MD3P DATA4_P DMO4P		MIPI 4th data lane positive output							
MCN CLKN CLK_N DCKN		MIPI clock negative output							
MCP CLKP MCP CLK_P DCKN		MIPI clock positive output							
<b>DVP Parallel Interface</b>									
D0 DO0 Y0		DVP data output port 0							
D1 DO1 Y1		DVP data output port 1							
D2 DO2 Y2		DVP data output port 2							
D3 DO3 Y3		DVP data output port 3							
D4 DO4 Y4		DVP data output port 4							
D5 DO5 Y5		DVP data output port 5							
D6 DO6 Y6		DVP data output port 6							
D7 DO7 Y7		DVP data output port 7							
D8 DO8 Y8		DVP data output port 8							
D9 DO9 Y9		DVP data output port 9							
D10 DO10 Y10		DVP data output port 10							
D11 DO11 Y11		DVP data output port 11							

[www.YDSCAM.com](http://www.YDSCAM.com) [sales@ydscam.com](mailto:sales@ydscam.com) Phone (WeChat, QQ): (+86) 177 2732 6718

All rights reserved @ YingDeShun Co. Ltd. Specifications subject to change without notice.

## Cameras Applications



### IMAGING DEVICES



## Camera Reliability Test

Reliability Inspection Item		Testing Method	Acceptance Criteria	
Category	Item			
Environmental	Storage Temperature	High 60°C 96 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 96 Hours	Temperature Chamber	No Abnormal Situation
	Operation Temperature	High 60°C 24 Hours	Temperature Chamber	No Abnormal Situation
		Low -20°C 24 Hours	Temperature Chamber	No Abnormal Situation
	Humidity	60°C 80% 24 Hours	Temperature Chamber	No Abnormal Situation
	Thermal Shock	High 60°C 0.5 Hours Low -20°C 0.5 Hours Cycling in 24 Hours	Temperature Chamber	No Abnormal Situation
Physical	Drop Test (Free Falling)	Without Package 60cm	10 Times on Wood Floor	Electrically Functional
		With Package 60cm	10 Times on Wood Floor	Electrically Functional
	Vibration Test	50Hz X-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Y-Axis 2mm 30min	Vibration Table	Electrically Functional
		50Hz Z-Axis 2mm 30min	Vibration Table	Electrically Functional
	Cable Tensile Strength Test	Loading Weight 4 kg 60 Seconds Cycling in 24 Hours	Tensile Testing Machine	Electrically Functional
Electrical	ESD Test	Contact Discharge 2 KV	ESD Testing Machine	Electrically Functional
		Air Discharge 4 KV	ESD Testing Machine	Electrically Functional
	Aging Test	On/Off 30 Seconds Cycling in 24 Hours	Power Switch	Electrically Functional
	USB Connector	On/Off 250 Times	Plug and Unplug	Electrically Functional





## Camera Inspection Standard

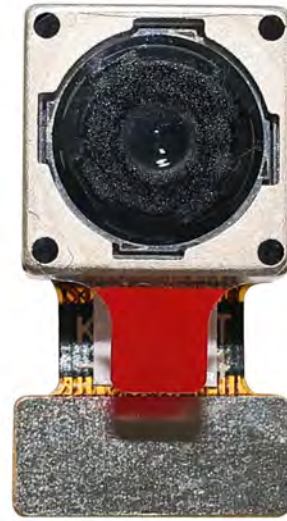
Inspection Item		Inspection Method	Standard of Inspection		
Category	Item				
Appearance	FPC/ PCB	Color	The Naked Eye	Major Difference is Not Allowed.	
		Be Torn/Chopped	The Naked Eye	Copper Crack Exposure is Not Allowed.	
		Marking	The Naked Eye	Clear, Recognizable (Within 30cm Distance)	
	Holder	Scratches	The Naked Eye	The Inside Crack Exposure is Not Allowed	
		Gap	The Naked Eye	Meet the Height Standard	
		Screw	The Naked Eye	Make Sure Screws Are Presented (If Any)	
		Damage	The Naked Eye	The Inside Crack Exposure is Not Allowed	
	Lens	Scratch	The Naked Eye	No Effect On Resolution Standard	
		Contamination	The Naked Eye	No Effect On Resolution Standard	
		Oil Film	The Naked Eye	No Effect On Resolution Standard	
		Cover Tape	The Naked Eye	No Issue On Appearance.	
	Function	Image	No Communication	Test Board	Not Allowed
			Bright Pixel	Black Board	Not Allowed In the Image Center
Dark Pixel			White board	Not Allowed In the Image Center	
Blurry			The Naked Eye	Not Allowed	
No Image			The Naked Eye	Not Allowed	
Vertical Line			The Naked Eye	Not Allowed	
Horizontal Line			The Naked Eye	Not Allowed	
Light Leakage			The Naked Eye	Not Allowed	
Blinking Image			The Naked Eye	Not Allowed	
Bruise			Inspection Jig	Not Allowed	
Resolution			Chart	Follows Outgoing Inspection Chart Standard	
Color			The Naked Eye	No Issue	
Noise			The Naked Eye	Not Allowed	
Corner Dark			The Naked Eye	Less Than 100px By 100px	
Color Resolution			The Naked Eye	No Issue	
Dimension	Height	The Naked Eye	Follows Approval Data Sheet		
	Width	The Naked Eye	Follows Approval Data Sheet		
	Length	The Naked Eye	Follows Approval Data Sheet		
	Overall	The Naked Eye	Follows Approval Data Sheet		

## YDSCAM Package Solutions

YDS Camera Module



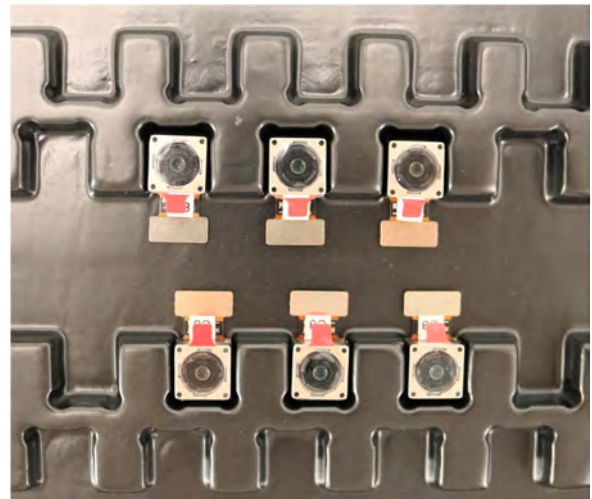
Complete with Lens Protection Film



Tray with Grid and Space

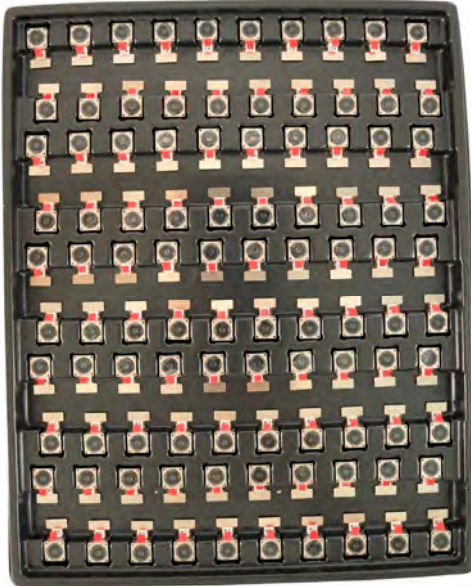


Place Cameras on the Tray

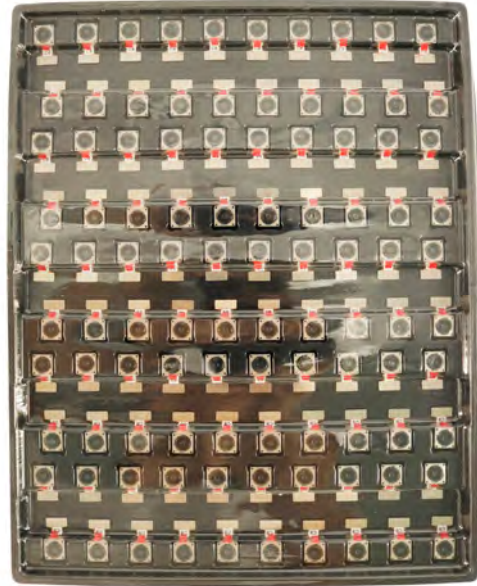


## YDSCAM Package Solutions

Full Tray of Cameras



Cover Tray with Lid



Place Tray into Anti-Static Bag



Vacuum the Anti-Static Bag



## YDSCAM Package Solutions

### Sealed Vacuum Anti-Static Bag with Labels

1. Model and Description 2. Quantity 3. Manufacturing Date Code 4. Caution



## YDSCAM Package Solutions

Place Foam Sheets Between Tray Bags



Foam Sheets are Larger Than Trays



Place Foam Sheets and Trays into Box



Foam Sheets are Tightly Fitting in Box



Seal the Carbon Box



Label the Carbon Shipping Box

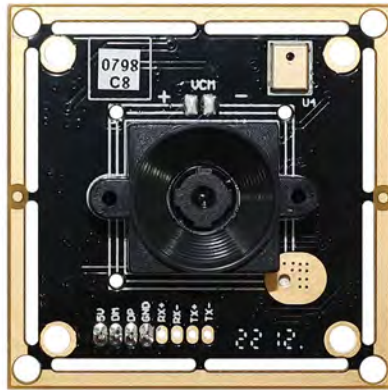




## YDSCAM Package Solutions

USB Camera Module

Complete with Lens Protection Film



Place Camera Sample into Anti-Static Bag

Place USB Cameras into Tray



Seal the Tray with Anti-Static Bag

Label the Carbon Shipping Box



## YDSCAM Package Solutions

Place Camera Sample into Anti-Static Bag



Place Connectors into Anti-Static Bag



Label the Sample Bags



Place Connectors into Reel



Place Samples into the Carbon Box



Place Connectors into the Carbon Box





# YDS CAMERA MODULE

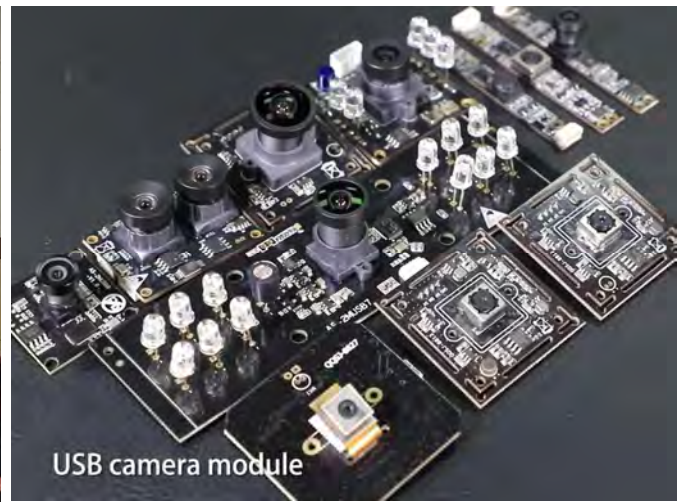
*your best camera partner*

## Company YDSCAM

YingDeShun Co. Ltd. (YDS) was established in 2017, a next-generation technology driven manufacturer specialized in research, design, and produce of audio and video products. YDS is occupying 20,000 square feet automated plants with 100 employees of annual throughput 30,000,000 units cameras.

YDS provides OEM, ODM design, contract manufacturing, and builds the camera products. You may provide the requirements to us, even with a hand draft, our sales and engineering work together to meet your needs. We consider ourselves your last-term partner in developing practical and innovative solutions.

Our team covers everything from initial concept development to mass produced product. YDS specializes in customized camera design, raw material, electronic engineering, firmware/software development, product testing, and packing design. Our experienced strategic supply systems offer a robust and dependable manufacturing capacity for orders of various sizes.



## Limited Warranty

YDS provides the following limited warranty if you purchased the Product(s) directly from YDS company or from YDS's website [www.YDSCAM.com](http://www.YDSCAM.com). Product(s) purchased from other sellers or sources are not covered by this Limited Warranty. YDS guarantees that the Product(s) will be free from defects in materials and workmanship under normal use for a period of one (1) year from the date you receive the product ("Warranty Period").

For all Product(s) that contain or develop material defects in materials or workmanship during the Warranty Period, YDS will, at its sole option, either: (i) repair the Product(s); (ii) replace the Product(s) with a new or refurbished Product(s) (replacement Product(s) being of identical model or functional equivalent); or (iii) provide you a refund of the price you paid for the Product(s).

This Limited Warranty of YDS is solely limited to repair and/or replacement on the terms set forth above. YDS is not reliable or responsible for any subsequent events.



[www.YDSCAM.com](http://www.YDSCAM.com) [sales@ydscam.com](mailto:sales@ydscam.com) Phone (WeChat, QQ): (+86) 177 2732 6718

All rights reserved @ YingDeShun Co. Ltd. Specifications subject to change without notice.





# YDS CAMERA MODULE

*your best camera partner*

## YDS Strength

### Powerful Factory



### Professional Service



### Promised Delivery



[www.YDSCAM.com](http://www.YDSCAM.com) [sales@ydscam.com](mailto:sales@ydscam.com) Phone (WeChat, QQ): (+86) 177 2732 6718

All rights reserved @ YingDeShun Co. Ltd. Specifications subject to change without notice.